



Advance Product Change Notification

202306009A : DIE ATTACH GLUE CHANGE DUE TO HENKEL 8388A DISCONTINUATION

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 16, 2023

Here is your personalized notification about a NXP general announcement. For detailed information we invite you to [view this notification online](#)

Management summary

For all MOA4 and MOA8 the used die attached glue Henkel LOCTITE ABLESTIK 8388A will change to Henkel LOCTITE ABLESTIK ABP 2035SCR.

The existing die attach glue has been discontinued by our supplier in December 2022. NXP could arrange enough die attach glue to be able to produce until November 2023.

The new die attach glue has been carefully selected to enhance the overall performance and durability of the product while ensuring compliance with the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) regulations.

Change Category

- Wafer Fab Process
- Assembly Process
- Product Marking
- Test Process
- Design
- Wafer Fab Materials
- Assembly Materials
- Mechanical Specification
- Test Equipment
- Errata
- Wafer Fab Location
- Assembly Location
- Packing/Shipping/Labeling
- Test Location
- Electrical spec./Test coverage
- Firmware
- Other

PCN Overview

Description

The die attach glue used between the chip and lead frame in chip on lead frame packaging serves as a bonding material to securely attach the chip to the lead frame.

This die attach adhesive is changed from Henkel LOCTITE ABLESTIK 8388A to Henkel LOCTITE ABLESTIK ABP 2035SCR for all MOA4 and MOA8 packages.

There are no changes to the form, fit and function of the MOA4 and MOA8 modules due to the changeover to the new die attach glue. The revised module continues to offer the same high-quality performance and reliability and complies with REACH standards. Attached to this notification, you will find the Qualification Plan which outlines the qualification procedures and criteria for the revised module.

Reason

The existing die attach glue has been discontinued by our supplier in December 2022. NXP could arrange enough die attach glue to be able to produce until November 2023.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Dec 31, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Timing and Logistics

The Self Qualification Report will be ready on Sep 04, 2023.

The Final PCN is planned to be issued on: Sep 04, 2023.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 16, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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